PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JARMO SAASKI	10/09/2018
JARKKO TORVINEN	10/09/2018
PASI RAAPPANA	10/09/2018
MIKKO HEIKKINEN	10/09/2018

RECEIVING PARTY DATA

Name:	TACTOTEK OY
Street Address:	AUTOMAATIOTIE 1,
City:	OULUNSALO
State/Country:	FINLAND
Postal Code:	90460

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16156008

CORRESPONDENCE DATA

Fax Number: (631)501-3526

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 631-501-5700

Email: docket@cdfslaw.com, kdugo@cdfslaw.com **Correspondent Name:** CARTER, DELUCA, FARRELL & SCHMIDT, LLP

Address Line 1: 445 BROAD HOLLOW ROAD

Address Line 2: SUITE 420

Address Line 4: MELVILLE, NEW YORK 11747

ATTORNEY DOCKET NUMBER:	44605-31 PCT US
NAME OF SUBMITTER:	ROBERT P. MICHAL
SIGNATURE:	/Robert P. Michal/
DATE SIGNED: 10/10/2018	
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 4

PATENT REEL: 047118 FRAME: 0021

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TITLE OF	MULTILAYER STRUCTURE WITH EMBEDDED MULTILAYER		
INVENTION:	ELECTRONICS		
As the below named invento	As the below named inventor, I hereby declare that:		
This declaration is directed to	D:		
☐ United States application	 ☑ The attached application, or ☐ United States application or PCT international application number filed on 		
The above-identified applica	tion was made or authorized to be made by me.		
I believe that I am the origin	al inventor or an original joint inventor of a claimed inven	tion in the application.	
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S. C. § 1001 by fine or imprisonment of not more than five (5) years, or both.			
WHEREAS, I, the below-identified Inventor, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter "Invention");			
WHEREAS, <u>TactoTek Oy</u> (hereinafter "Assignee") having place of business at: <u>Automatiotie 1, 90460 Oulunsalo</u> , <u>Finland</u> , is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States or its territorial possessions and in any and all foreign countries;			
acknowledged, and for other	messeth, that in consideration of the sum of ONE DOLLA good and valuable consideration;		
I hereby assign, sell and transfer my above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said Invention, and in and to any and all reissues and reexaminations thereof, which may be granted or have granted for said Invention, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;			
And I hereby authorize and request the Commissioner of Patents and Trademarks to issue any Untied States Letters Patent which my issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;			
And I further agree to sign and execute all necessary and lawful further documents, including applications for foreign patents, for filing divisions, continuations, and continuations-in-part of said application for patent and/or for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its successors and designees may from time to time require and prepare at its own expense.			
The undersigned hereby grants the firm of CARTER, DELUCA, FARRELL & SCHMIDT, LLP, located at 445 Broad Hollow Road, Suite 420, Melville, New York 11747, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.			
LEGAL NAME	Inventor: Jarmo SÄÄSKI	Date: 7.10.2018	
OF INVENTOR	Signature:	Date:	

CARTER, DELUCA, FARRELL & SCHMIDT, LLP 445 BROAD HOLLOW ROAD, SUITE 420 MELVILLE, NEW YORK 11747

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	or PCT international application number	led on	
The above-identified applicati	on was made or authorized to be made by me.		
	inventor or an original joint inventor of a claimed inventi	on in the application.	
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lidentified above and described	identified inventor, have invented certain new and useful in the above-identified patent application(s) and/or pater		
WHEREAS, TactoTek Oy (hereinafter "Assignee") having place of business at: Automatiotie 1, 90460 Oulunsato, Finland, is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States or its territorial possessions and in any and all foreign countries;			
and for other	NOW, this indenture witnesseth, that in consideration of the sum of ONE DOLLAR (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration;		
I hereby assign, sell and transfer my above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Patent of the United States, and countries foreign thereto, which may be granted for said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted or have granted for said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted or have granted for said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted to said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted for said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted for said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted to said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted to said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted for said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted for said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted for said Invention, and in and to any and all priority reissues and reexaminations thereof, and the priority reissues are respectively.			
And I hereby authorize and request the Commissioner of Patents and Trademarks to issue any Untied States Letters Patent which my issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;			
And I further agree to sign and execute all necessary and lawful further documents, including applications for toreign patents, for filing divisions, continuations, and continuations-in-part of said application for patent and/or for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its successors and reissues may from time to time require and prepare at its own expense.			
The undersigned hereby grants the firm of CARTER, DELUCA, FARRELL & SCHMIDT, LLP, located at 445 Broad Hollow Road, Suite 420, Melville. New York 11747, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.			
LEGAL NAME	Inventor: Jarkko TORVINEN Signature: Jarko 2	Date: 9.10.2018	
OF INVENTOR	Signature: Willer 2		

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I believe that I am the origina	l inventor or an original joint inventor of a claimed inventi	ion in the application.	
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identified above and describe	-identified Inventor, have invented certain new and useful d in the above-identified patent application(s) and/or pater	(0) (11010	
WHEREAS, TactoTek Oy (hereinafter "Assignee") having place of business at: Automaatiotie 1, 90460 Oulunsalo. Finland, is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States or its territorial possessions and in any and all foreign countries:			
NOW, this indenture witnesseth, that in consideration of the sum of ONE DOLLAR (\$1.00), the receipt of which is hereby			
I hereby assign, sell and transfer my above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Patent of the United States, and countries foreign thereto, which may be granted for said Invention, and in and to any and all priority reissues and reexaminations thereof, which may be granted or have granted for said Invention, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignce:			
And I hereby authorize and request the Commissioner of Patents and Trademarks to issue any Untied States Letters Patent which my issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;			
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LEGAL NAME OF INVENTOR	Inventor: Pasi RAAPPANA Signature:	Date: 9.10.2018	

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This declaration is directed to	:		
☐ United States application	or PCT international application numberf	ited on	
	ion was made or authorized to be made by me.		
I believe that I am the origina	l inventor or an original joint inventor of a claimed invent	ion in the application.	
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S. C. § 1001 by fine or imprisonment of not more than five (5) years, or both.			
WHEREAS, I, the below-identified Inventor, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter "Invention");			
WHEREAS, <u>TactoTek Oy</u> (hereinafter "Assignce") having place of business at: <u>Automaatiotie 1, 90460 Oulunsalo</u> , <u>Finland</u> , is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States or its territorial possessions and in any and all foreign countries;			
NOW, this indenture witnesseth, that in consideration of the sum of ONE DOLLAR (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration;			
I hereby assign, sell and transfer my above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said Invention, and in and to any and all reissues and reexaminations thereof, which may be granted or have granted for said Invention, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignce;			
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LEGAL NAME OF INVENTOR	Inventor: Mikko HERKINEN Signature:	Date: 9.10.2618	

CARTER, DELUCA, FARRELL & SCHMIDT, LLP 445 BROAD HOLLOW ROAD, SUITE 420 MELVILLE, NEW YORK 11747

RECORDED: 10/10/2018